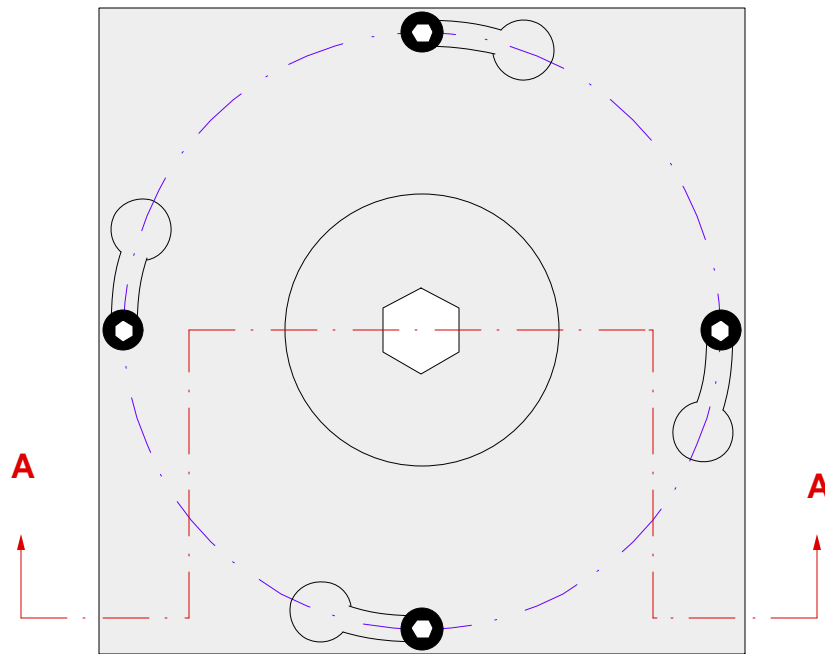


GHz BGA Socket - Direct mount, solderless

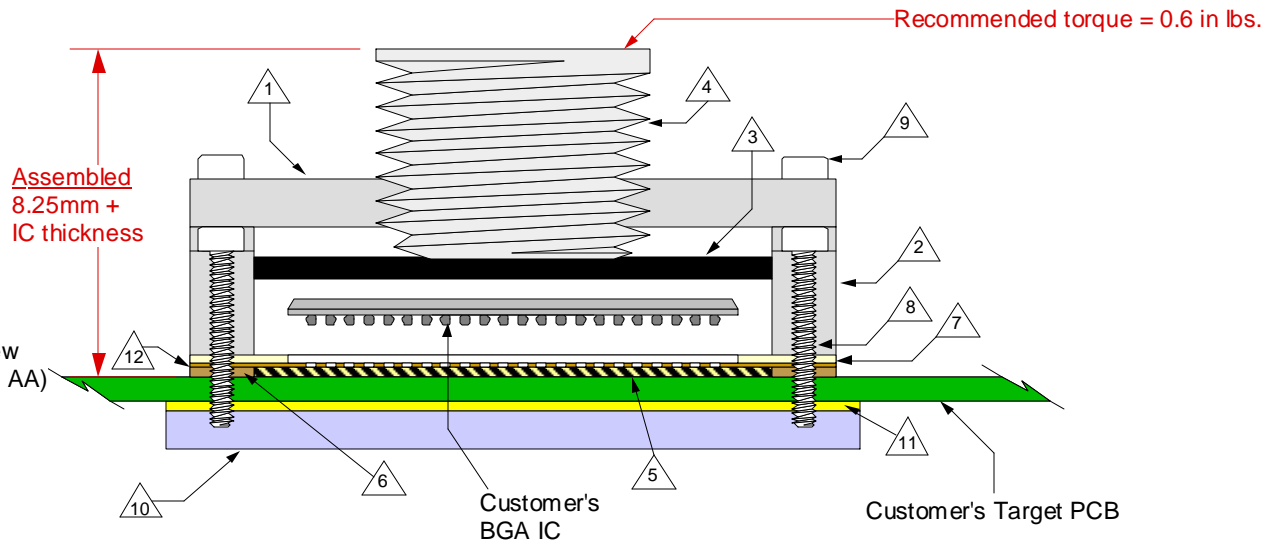
Features

- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Easily removable swivel socket lid


Top View



Side View
(Section AA)



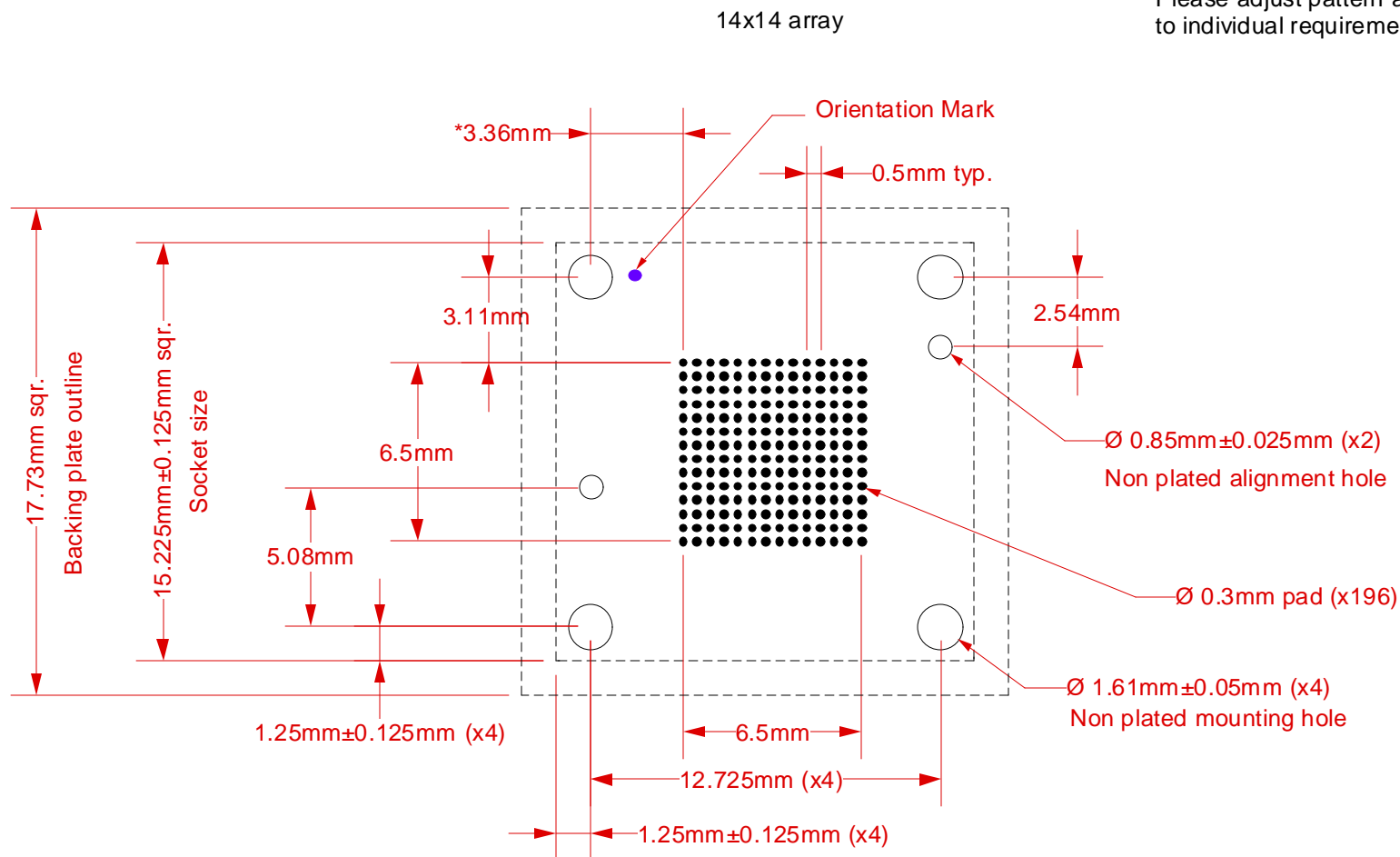
- △ 1 Socket Lid: Black anodized Aluminum. Thickness = 2.5mm.
- △ 2 Socket base: Black anodized Aluminum. Thickness = 5mm.
- △ 3 Compression Plate: Black anodized Aluminum. Thickness = 2.5mm.
- △ 4 Compression screw: Clear anodized Aluminum. Thickness = 5mm, Hex socket = 5mm.
- △ 5 Elastomer: 20 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.5mm.
- △ 6 Elastomer Guide: Non-clad FR4. Thickness = 0.475mm.
- △ 7 IC guide: Ultem 2300.
- △ 8 Socket base screw: Socket head cap, alloy steel with black oxide finish, 0-80 fine thread, 9.525mm long.
- △ 9 Socket lid screw: Shoulder screw, 18-8 SS, 0-80 fine thread.
- △ 10 Backing Plate: Aluminum. Thickness = 6.35mm
- △ 11 Insulating Plate: FR4. Thickness = 1.58mm.
- △ 12 Ball Guide: Kapton. Thickness = 0.003".

 <p>© 2005 IRONWOOD ELECTRONICS, INC. Tele: (952) 229-8200 www.ironwoodelectronics.com</p>	SG-BGA-7045 Drawing	Status: Released	Scale: -	Rev: B
	Drawing: E Smolentseva	Date: 3/15/05		
	File: SG-BGA-7045 Dwg.mcd	Modified: 6/2/09, AE		

All tolerances: $\pm 0.125\text{mm}$ (unless stated otherwise). Materials and specifications are subject to change without notice.

***Note: BGA pattern is not symmetrical with respect to the mounting holes.**

Note: Full BGA pattern shown.
Please adjust pattern according to individual requirements.



Target PCB Recommendations


Total thickness: 1.6mm min.

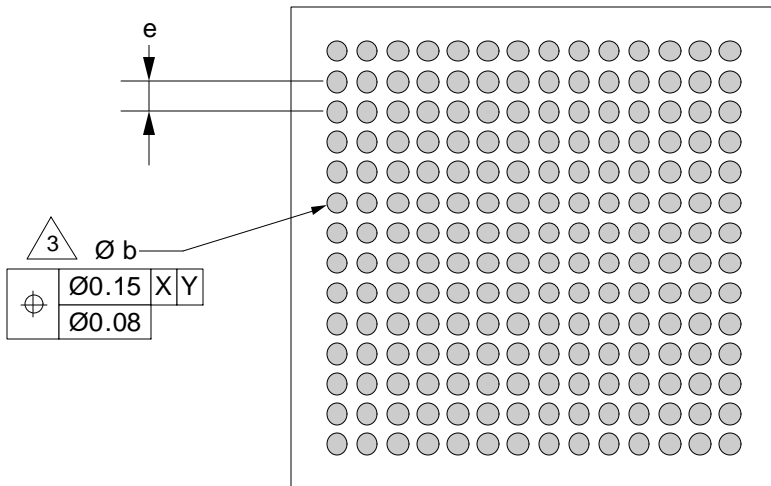
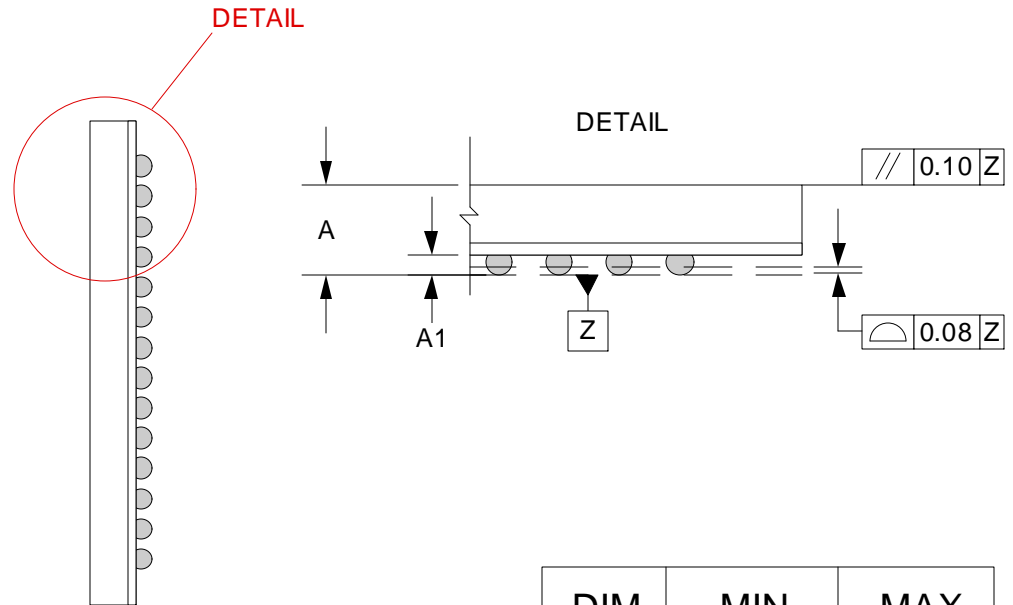
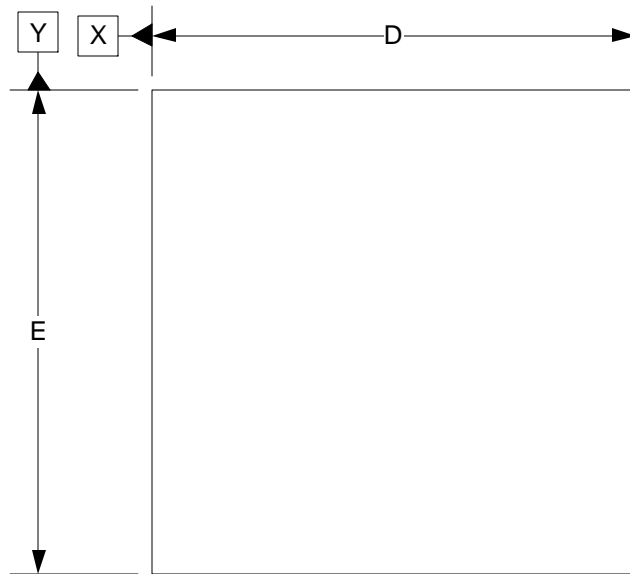
Plating: Gold or Solder finish

PCB Pad height: Same or higher than solder mask

All dimensions are in mm unless stated otherwise

Recommended PCB Layout Tolerances: ±0.025mm [±0.001"] unless stated otherwise.

	SG-BGA-7045 Drawing	Status: Released	Scale: 4:1	Rev: B
	© 2005 IRONWOOD ELECTRONICS, INC. Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: E Smolentseva		Date: 3/15/05
		File: SG-BGA-7045 Dwg.mcd	Modified: 6/2/09, AE	



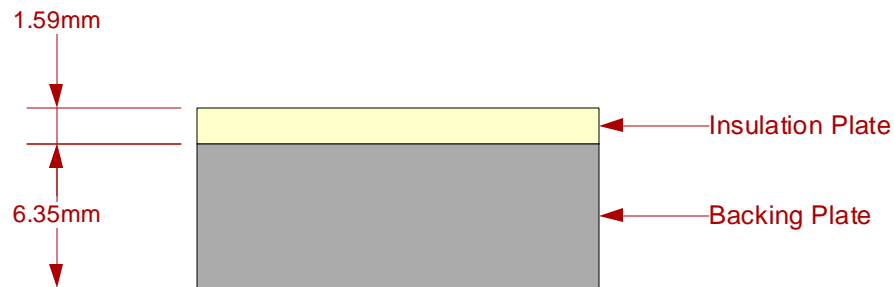
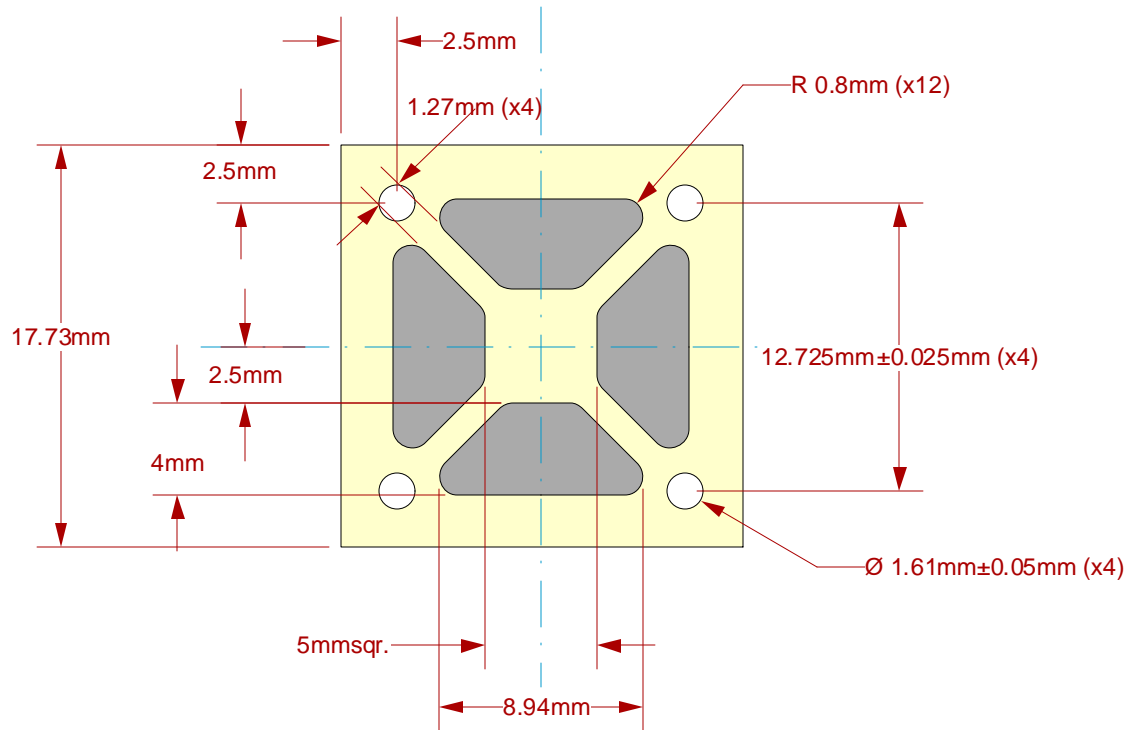
1. Dimensions are in millimeters.
 2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
- Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
 - Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
 - Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		1.1
A1	0.15	0.25
b		0.35
D	8.0 BSC	
E	8.0 BSC	
e	0.5 BSC	


14 X 14 array

All dimensions are in mm unless stated otherwise

	SG-BGA-7045 Drawing	Status: Released	Scale: 1:0.125	Rev: B
	© 2005 IRONWOOD ELECTRONICS, INC. Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: E Smolentseva		Date: 3/15/05
		File: SG-BGA-7045 Dwg.mcd	Modified: 6/2/09, AE	



All dimensions are in mm unless stated otherwise

	SG-BGA-7045 Drawing	Status: Released	Scale: -	Rev: B
	© 2005 IRONWOOD ELECTRONICS, INC. Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: E Smolentseva		Date: 3/15/05
		File: SG-BGA-7045 Dwg.mcd		Modified: 6/2/09